

ABSTRACT

5 A ceramic package and a chip resistor obtained by  
forming, on a plastic ceramic green sheet comprising 100  
parts by weight of a ceramic powder mainly composed of  
borosilicate glass, into which 10 to 30 parts by weight  
of an acrylic copolymer obtained by polymerizing 100  
parts by weight of a (meth)acrylic acid ester and 1 to 10  
parts by weight of a monomer having a functional group of  
10 a hydroxyl group, acid amide group, or amino group and  
having a Tg in the range of  $-30^{\circ}\text{C}$  to  $+10^{\circ}\text{C}$  is compounded,  
a conductor layer using a plastic conductive paste  
obtained by compounding, into 100 parts by weight of a  
conductive powder, 5 to 20 parts a mixture of an acrylic  
15 copolymer having a Tg of not more than  $-30^{\circ}\text{C}$  and an  
ethylcellulose-based binder, press forming the resultant  
single layer of ceramic green sheet, and calcining the  
resultant ceramic green sheet having the integrally  
formed bottom, opening and opening circumferential edge  
20 and a method for producing the same.